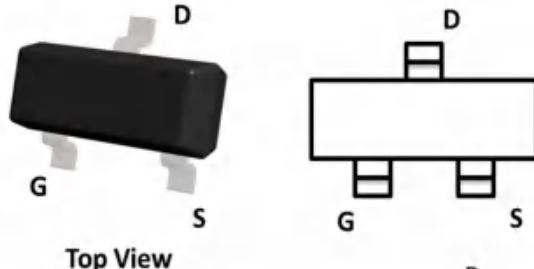


Feature

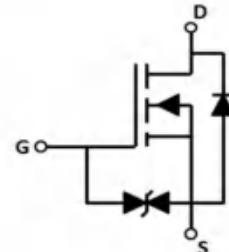
- 20V,6.8A
- $R_{DS(on)} < 15\text{ m}\Omega$ @ $V_{GS}=4.5\text{ V}$ TYP=13 mΩ
- $R_{DS(on)} < 22\text{ m}\Omega$ @ $V_{GS}=2.5\text{ V}$ TYP=16 mΩ
- Advanced Trench Technology
- Lead free product is acquired
- ESD>2KV



Application

- Interfacing Switching
- Load Switching
- Power management

SOT-23



Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity (PCS) |
|----------------|--------|----------------|-----------|------------|----------------|
| 3416 | AP3416 | Sot-23 | 7 inch | - | 3000 |

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|--|-----------------|----------|------|
| Drain-Source Voltage | V_{DS} | 20 | V |
| Gate-Source Voltage | V_{GS} | ± 10 | V |
| Continuous Drain Current ($T_a = 25^\circ\text{C}$) | I_D | 6.8 | A |
| Continuous Drain Current ($T_a = 70^\circ\text{C}$) | I_D | 4.4 | A |
| Pulsed Drain Current | I_{DM} | 27 | A |
| Power Dissipation | P_D | 1.6 | W |
| Thermal Resistance from Junction to Ambient ⁽⁴⁾ | $R_{\theta JA}$ | '78 | °C/W |
| Junction Temperature | T_J | 150 | °C |
| Storage Temperature | T_{STG} | -55~+150 | °C |

MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Test Condition | Min | Type | Max | Unit |
|---|---------------|--|-----|------|------------|-----------|
| Static Characteristics | | | | | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 20 | - | - | V |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 20V, V_{GS} = 0V$ | - | - | 1 | μA |
| Gate-body leakage current | I_{GSS} | $V_{GS} = \pm 10V, V_{DS} = 0V$ | - | - | ± 5000 | nA |
| Gate threshold voltage ⁽³⁾ | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 0.3 | 0.7 | 1.0 | V |
| Drain-source on-resistance ⁽³⁾ | $R_{DS(on)}$ | $V_{GS} = 4.5V, I_D = 6A$ | - | 13 | 15 | $m\Omega$ |
| | | $V_{GS} = 2.5V, I_D = 3A$ | - | 16 | 22 | |
| Dynamic characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$ | - | 780 | - | pF |
| Output Capacitance | C_{oss} | | - | 140 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 80 | - | |
| Switching characteristics | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 10V, I_D = 3.5A,$ $V_{GS} = 4.5V, R_G = 10\Omega$ | - | 9 | - | ns |
| Turn-on rise time | t_r | | - | 30 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 35 | - | |
| Turn-off fall time | t_f | | - | 10 | - | |
| Total Gate Charge | Q_g | $V_{DS} = 10V, I_D = 3.5A,$ $V_{GS} = 4.5V$ | - | 11 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 2.3 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 2.9 | - | |
| Source-Drain Diode characteristics | | | | | | |
| Diode Forward voltage ⁽³⁾ | V_{DS} | $V_{GS} = 0V, I_S = 4A$ | - | - | 1.2 | V |
| Diode Forward current ⁽⁴⁾ | I_S | | - | - | 6.8 | A |

Notes:

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. Pulse Test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. Surface Mounted on FR4 Board, $t \leq 10$ sec

Test Circuit

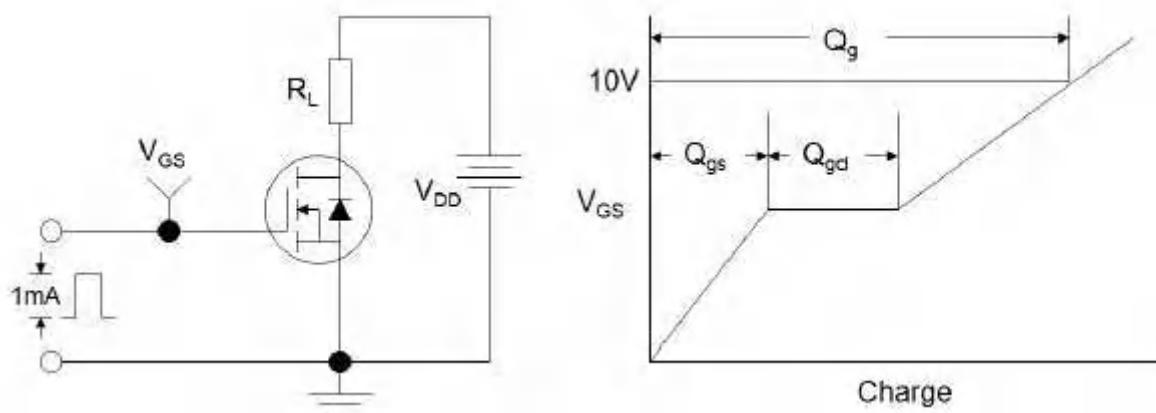


Figure1:Gate Charge Test Circuit & Waveform

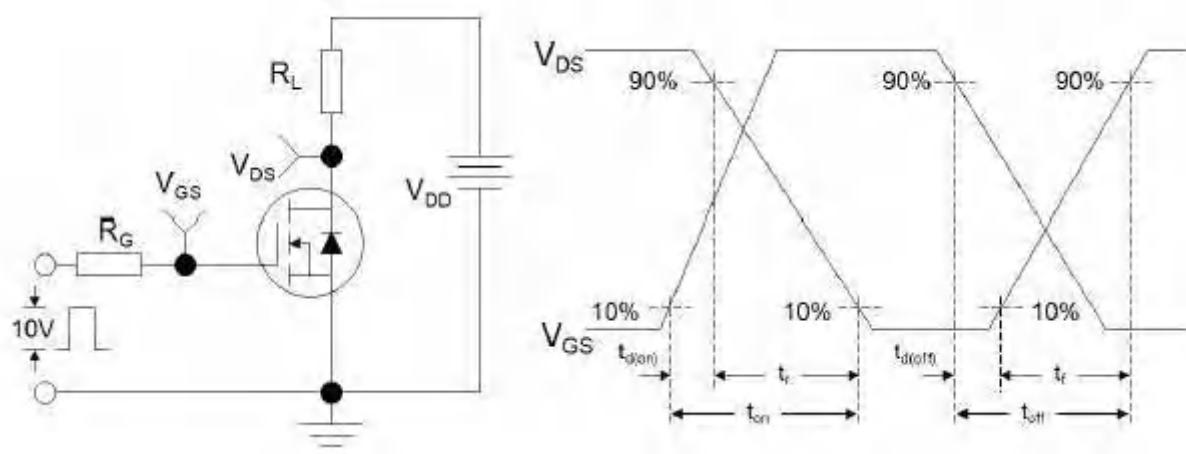


Figure 2: Resistive Switching Test Circuit & Waveforms

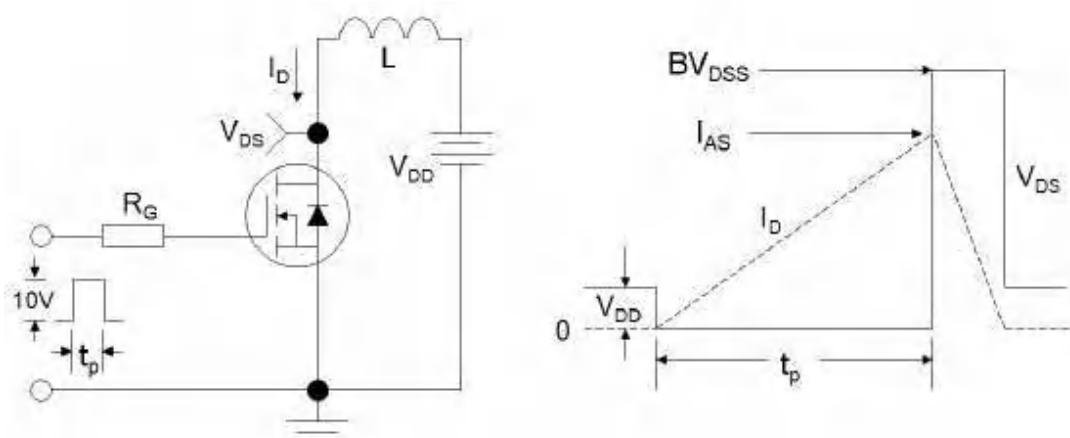


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Typical Performance Characteristics

Figure 1: Output Characteristics

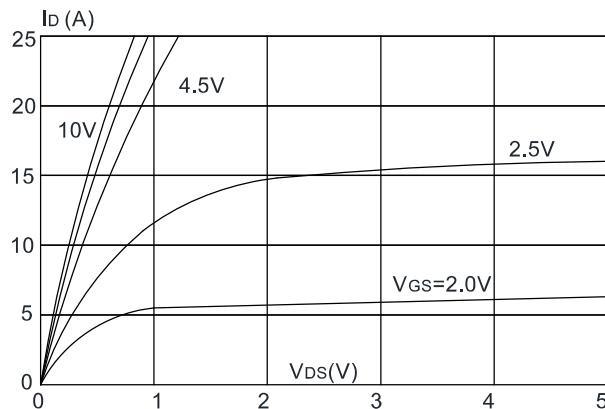


Figure 3: On-resistance vs. Drain Current

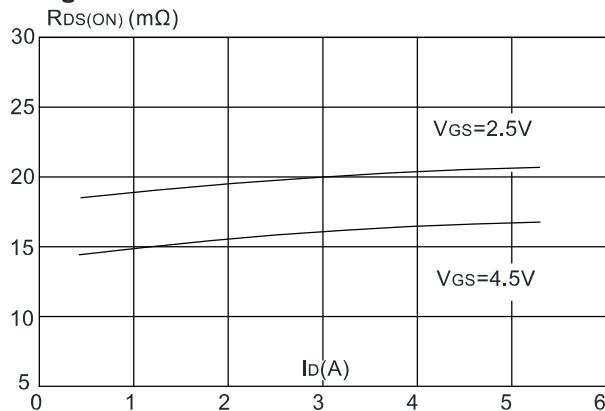


Figure 5: Gate Charge Characteristics

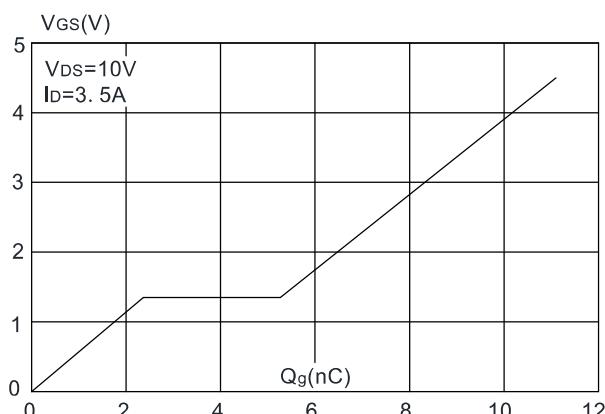


Figure 2: Typical Transfer Characteristics

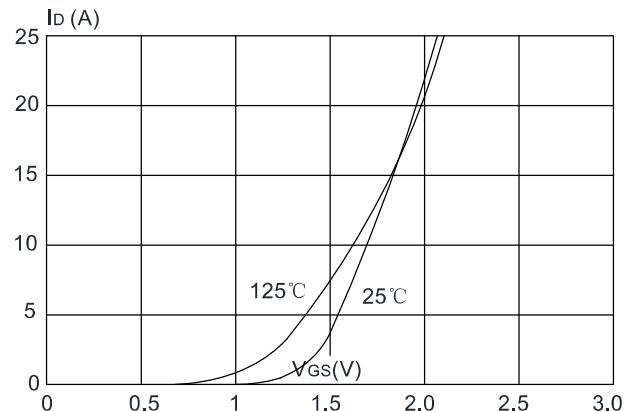


Figure 4: Body Diode Characteristics

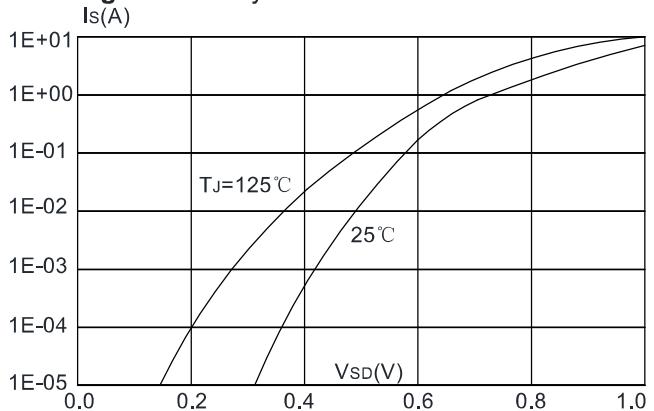


Figure 6: Capacitance Characteristics

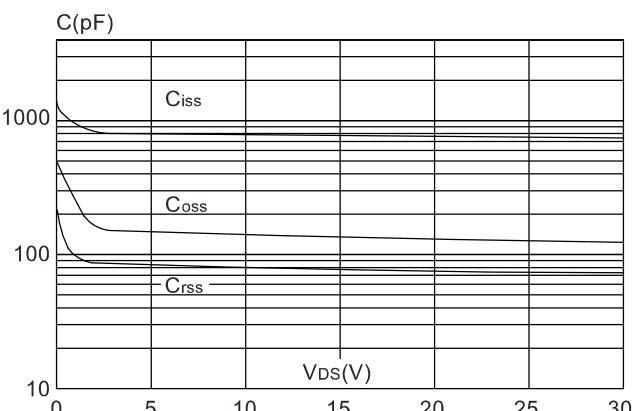


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

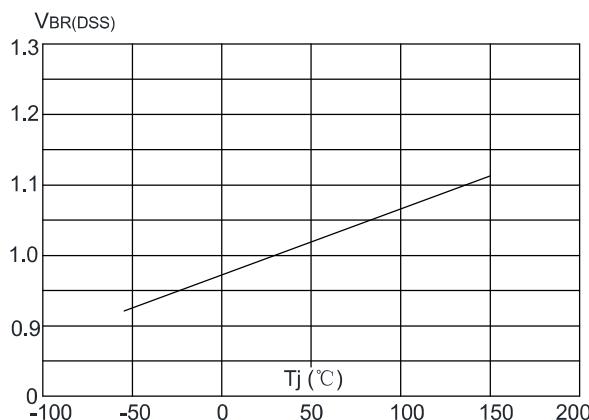


Figure 8: Normalized on Resistance vs. Junction Temperature

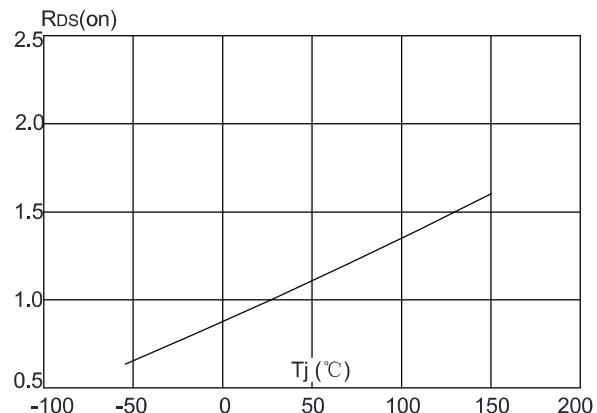


Figure 9: Maximum Safe Operating Area

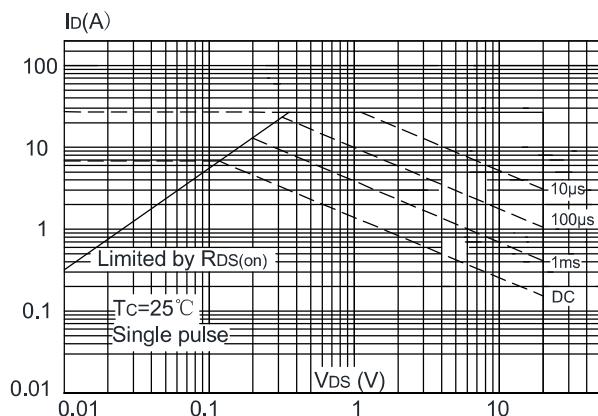


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

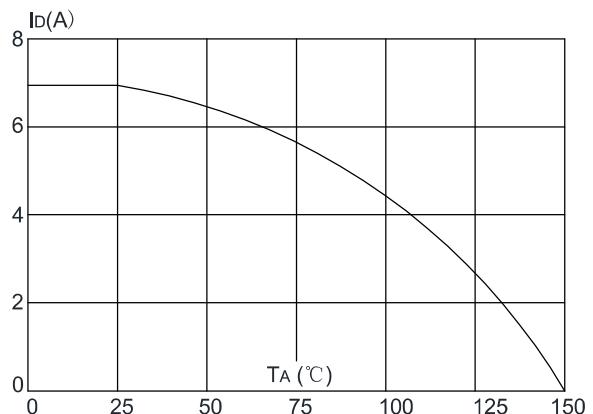
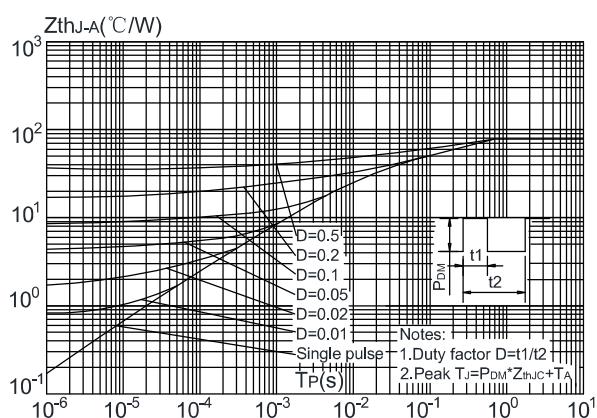
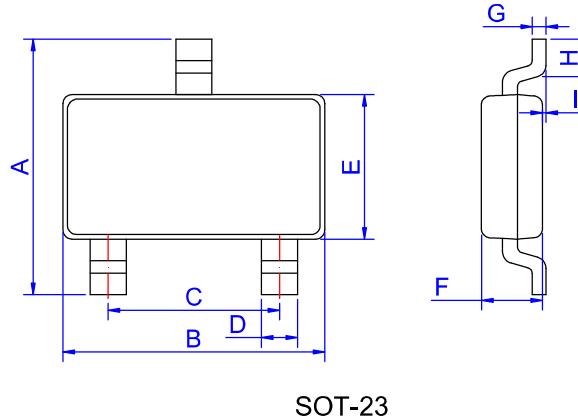


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

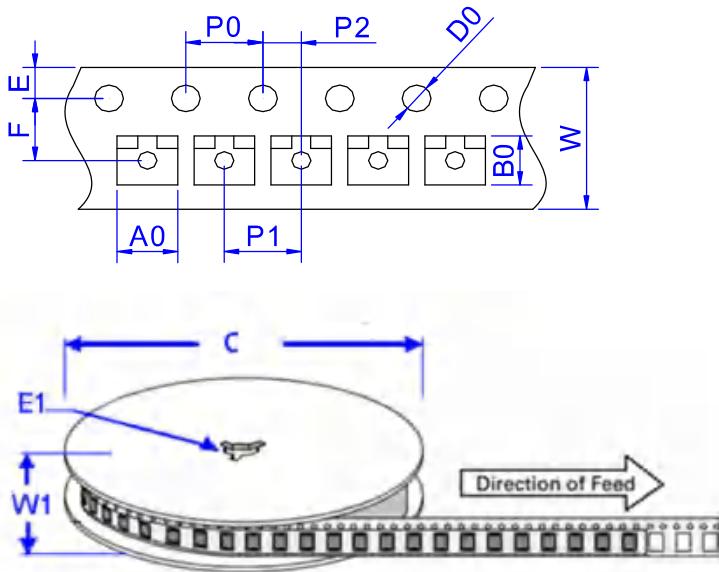


SOT-23 Package Information



| Ref. | Dimensions | | | | | |
|------|-------------|------|------|-----------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 2.30 | 2.40 | 2.50 | 0.091 | 0.095 | 0.098 |
| B | 2.80 | 2.90 | 3.00 | 0.110 | 0.114 | 0.118 |
| C | 1.90 REF | | | 0.075 REF | | |
| D | 0.35 | 0.40 | 0.45 | 0.014 | 0.016 | 0.018 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| F | 0.90 | 1.00 | 1.10 | 0.035 | 0.039 | 0.043 |
| G | | 0.10 | 0.15 | | 0.004 | 0.006 |
| H | 0.20 | | | 0.008 | | |
| I | 0 | | 0.10 | 0 | | 0.004 |

Package Information-SOT-23



| Ref. | Dimensions | |
|------|-------------|---------------|
| | Millimeters | Inches |
| A0 | 3.15 ± 0.3 | 0.124 ± 0.012 |
| B0 | 2.77 ± 0.3 | 0.109 ± 0.012 |
| C | 178 | 7.0 |
| D0 | 1.50 ± 0.1 | 0.059 ± 0.004 |
| E | 1.75 ± 0.2 | 0.069 ± 0.008 |
| E1 | 13.3 ± 0.3 | 0.524 ± 0.012 |
| F | 3.5 ± 0.2 | 0.138 ± 0.008 |
| P0 | 4.00 ± 0.2 | 0.157 ± 0.008 |
| P1 | 4.00 ± 0.2 | 0.157 ± 0.008 |
| P2 | 2.00 ± 0.2 | 0.079 ± 0.008 |
| W | 8.00 ± 0.2 | 0.315 ± 0.008 |
| W1 | 11.5 ± 1.0 | 0.453 ± 0.039 |